



## Final Product Change Notification

201810026F01

**Issue Date:** 20-Dec-2018  
**Effective Date:** 19-Mar-2019

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

**This notice is NXP Company Proprietary.**



# QUALITY

### Management Summary

Cu Wire is being added as a wirebond material option for LPC18xx, LPC18x0, LPC43xx and LPC43x0 in LQFP packages at assembly site NXP-ATKH.

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input type="checkbox"/> Other                         |  |   |   |

LPC18xx, LPC43xx LQFP  
Package Cu Wire  
Qualification for NXP-  
ATKH

### Description of Change

Copper wire has been qualified and will be added as a wirebond material. Upon effective date, NXP will begin shipping product with copper wire.

See attached Self Qualification Reports (SQR) for details of the affected part numbers, material changes and qualification test results.

Samples of the following superset part numbers will be available.  
LPC4357JBD208, LPC4337JBD144, LPC4330FBD144,  
LPC1857JBD208, LPC1837JBD144, LPC1830FBD144,  
LPC1820FBD144/3D, LPC1820FBD144,  
LPC43S20BD144/CP3332

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-08

**Reason for Change**

Adding Copper wire is required to mitigate against raw material cost increases and for supply assurance.

**Identification of Affected Products**

Top side marking

Product version is incremented. See marking details in attached Self Qualification Report (SQR) document.

**Product Availability**

**Sample Information**

Samples are available from 31-Dec-2018

Sample requests can be sent to the email address below in Contact and Support.

**Production**

Planned first shipment 20-Mar-2019

**Anticipated Impact on Form, Fit, Function, Reliability or Quality**

Wire composition is the only change. No Impact to form, fit or function. Reliability is equivalent or improved.

**Data Sheet Revision**

No impact to existing datasheet

**Disposition of Old Products**

Existing inventory will be shipped until depleted

**Additional information**

**Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 19-Jan-2019.

**Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

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**Affected Part Numbers**

LPC4330FBD144,551  
LPC18557JBD208E  
LPC4320FBD144,551  
LPC1830FBD144,551  
LPC1820FBD144,551  
LPC4353JBD208E  
LPC4357JBD208E  
LPC4312JBD144E  
LPC4313JBD144E  
LPC4317JBD144E  
LPC4322JBD144E  
LPC4323JBD144E  
LPC4327JBD144E  
LPC4333JBD144E  
LPC4337JBD144E  
LPC1817JBD144E  
LPC1833JBD144E  
LPC1837JBD144E  
LPC1857JBD208E  
LPC43S20FBD144E  
LPC43S30FBD144E  
LPC18S37JBD144E  
LPC43S37JBD144E